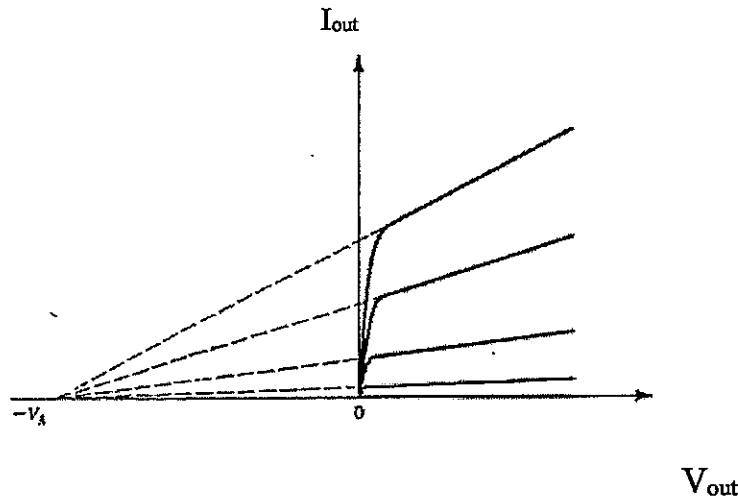


※ 考生請注意：本試題可使用計算機。請於答案卷(卡)作答，於本試題紙上作答者，不予計分。

1. An n-type semiconductor is under thermal equilibrium and has an electron distribution of $n(x) = n_0 \exp(-x/L_n)$, where L is its length, n_0 and L_n are constant, and $0 \leq x \leq L$.
 - (a) Derive and sketch its potential distribution $V(x)$ with the potential of Fermi level at $x = 0$ as the voltage reference. (10%)
 - (b) Find the ratio of drift currents at $x = 0$ and $x = L$. (5%)
2. Draw the possible energy band diagram of a Si pn junction under light irradiation ($h\nu > E_g$) in open-circuit condition. What could be the maximum value of the open-circuit voltage? Why? (15%)
3. Explain the "Schottky effect" and "Fermi level pinning" which might occur in metal-semiconductor (MS) contacts, respectively. (10%)
4. Please use energy band diagram to explain why bipolar junction transistors (BJTs) could serve as a current amplifier. (10%)
5. Consider a planar N-channel MOSFET with a metal gate with work function $\Phi_{\text{metal}} = 4.61\text{V}$ fabricated on P-type silicon wafer with uniform doping concentration $N_A = 10^{17}\text{cm}^{-3}$. The SiO_2 gate dielectric thickness (T_{ox}) is 1.5nm. The MOS transistor is $10\mu\text{m}$ wide (W) and 100nm long (L). The threshold voltage (V_t) at room temperature is 0.4V.
 - (a) How would V_t change if Φ_{metal} is increased to 4.81V (5%)?
 - A. Increases to 0.6V
 - B. Does not change
 - C. Decreases to 0.2V
 - D. Decreases by an amount that is smaller than 0.2V
 - (b) Which of the following statements is TRUE if T_{ox} is doubled (3.0nm) (5%)?
 - A. The body effect factor γ decreases
 - B. V_t increases
 - C. The gate capacitance C_{ox} increases
 - D. The flatband voltage V_{fb} decreases
 - (c) Which of the following statements is TRUE if we increase the doping concentration N_A to 10^{18}cm^{-3} (5%)?
 - A. V_t decreases
 - B. Punch-through will be larger (more severe)
 - C. Body effect factor γ decreases
 - D. Mobility μ will be smaller (degraded)

- (d) Which of the following statements is TRUE if we replace the gate dielectric with HfON with relative dielectric constant $\epsilon_r=16$ with twice the thickness of the original SiO_2 (5%)?
- A. Punch-through will be larger (more severe)
 - B. The gate leakage current will be larger
 - C. The gate capacitance C_{ox} increases
 - D. Mobility μ will be larger (better)

6. Consider the following transistor output characteristics



- (a) If this set of curves were MOSFET drain current (i_D) versus drain voltage (v_{DS}) characteristics for different gate biases (v_{GS}), what is the name of the physical phenomenon responsible for the non-zero slope at high v_{DS} (5%)?
 - (b) Following (a), explain the physical phenomenon that results in such non-zero slope (5%).
 - (c) If the above set of curves were BJT collector current (i_C) versus collector voltage (v_{CE}) characteristics for different base current (i_B), what is the name of the physical phenomenon responsible for the non-zero slope at high V_{ds} (5%)?
 - (d) Following (c), explain the physical phenomenon that results in such non-zero slope (5%).
 - (e) If the curves intersect at a negative voltage $-V_A$, express the output resistance (r_o) as function of V_A . Consider a BJT with collector current i_{c0} near the edge of saturation (5%).
7. List three possible ways to reduce short channel effects (which causes drain-induced barrier lowering, sub-threshold slope degradation, and V_t roll-off) in enhancement-mode MOSFETs (5%).